Title (en)
DETERMINING A REMAINING INTENDED SERVICE LIFE OF A SEMICONDUCTOR MODULE

Title (de)
BESTIMMEN EINER NOCH VERBLEIBENDEN BESTIMMUNGSGEMÄSSEN NUTZBARKEIT EINES HALBLEITERMODULS

Title (fr)
DÉTERMINATION DE LA DURÉE DE SERVICE PRÉVUE RESTANTE D'UN MODULE À SEMI-CONDUCTEUR

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Application
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Abstract (en)
[origin: WO2020156733A1] The invention relates to a method for determining the remaining usability of a semiconductor module (24) in normal use, which semiconductor module is thermally coupled to a cooling device (20), in which method a predefined electrical load (34) is applied to the semiconductor module (24) while predefined cooling is effected by the cooling device (20), a temperature (36) of a semiconductor element (28) of the semiconductor module (24) is sensed at least for the predefined electrical load (34) on the semiconductor module (24), the sensed temperature (36) is compared with a comparison temperature (40) in a first comparison, the comparison temperature (40) being assigned to the predefined electrical load (34) with the predefined cooling, and prediction data (44) for the remaining usability of the semiconductor module (24) in normal use up to a usability end are determined at least in accordance with the first comparison.

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